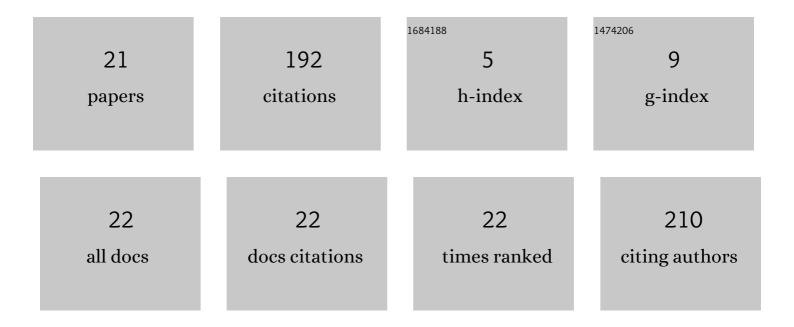
Dag R Andersson

List of Publications by Year in descending order

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| # | Article | IF | CITATIONS |
|----|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----|-----------|
| 1 | Current Problems and Possible Solutions in High-Temperature Lead-Free Soldering. Journal of Materials Engineering and Performance, 2012, 21, 629-637. | 2.5 | 68 |
| 2 | Effect of PCB cracks on thermal cycling reliability of passive microelectronic components with single-grained solder joints. Microelectronics Reliability, 2019, 93, 61-71. | 1.7 | 23 |
| 3 | Significance of intermediate production processes in life cycle assessment of electronic products assessed using a generic compact model. Journal of Cleaner Production, 2005, 13, 1269-1279. | 9.3 | 22 |
| 4 | Thermal Cycling Aging Effect on the Shear Strength, Microstructure, Intermetallic Compounds (IMC) and Crack Initiation and Propagation of Reflow Soldered Sn-3.8Ag-0.7Cu and Wave Soldered Sn-3.5Ag Ceramic Chip Components. IEEE Transactions on Components and Packaging Technologies, 2008, 31, 331-344. | 1.3 | 21 |
| 5 | Mutiphysics study of RF/microwave planar devices: Effect of the input signal power. , 2014, , . | | 12 |
| 6 | The shear strength of nano-Ag sintered joints and the use of Ag interconnects in the design and manufacture of SiGe-based thermo-electric modules. Microelectronics Reliability, 2015, 55, 722-732. | 1.7 | 10 |
| 7 | Simulations of the impact of single-grained lead-free solder joints on the reliability of ball Grid Array components. , 2017, , . | | 8 |
| 8 | Thermo-mechanical simulations of SiC power modules with single and double sided cooling. , 2015, , . | | 5 |
| 9 | COSIVU $\hat{a} \in \raiset$ Compact, smart and reliable drive unit for fully electric vehicles. , 2016, , . | | 5 |
| 10 | Printed circuit boards for leadâ€free soldering: materials and failure mechanisms. Circuit World, 2007, 33, 10-16. | 0.9 | 4 |
| 11 | UML modelling concepts of HAZOP to enhance the ability to identify emerging risks. Journal of Risk Research, 2013, 16, 421-432. | 2.6 | 3 |
| 12 | On the formation and propagation of laminate cracks and their influence on the fatigue lives of solder joints. , 2018, , . | | 3 |
| 13 | Thermal Simulations and Experimental Verification of Power Modules Designed for Double Sided Cooling. , 2016, , . | | 2 |
| 14 | Effect of different temperature cycling profiles on the crack initiation and propagation of Sn–3.5Ag wave soldered solder joints. Microelectronics Reliability, 2007, 47, 266-272. | 1.7 | 1 |
| 15 | Thermo-mechanical simulations and measurements on high temperature interconnections. , 2011, , . | | 1 |
| 16 | Modeling of SiC power modules with double sided cooling. , 2014, , . | | 1 |
| 17 | SMARTER-SI - Smart access to manufacturing for Systems Integration. , 2017, , . | | 1 |
| 18 | The shear strength of nano-Ag solders and the use of Ag interconnects in the design and manufacture of SiCe based thermo electric modules _ 2014 | | 0 |

of SiGe-based thermo-electric modules. , 2014, , .

2

| # | Article | IF | CITATIONS |
|----|---------------------------------------------------------------------------------------------------------------------------------------------|----|-----------|
| 19 | Model verification of heat exchangers in a flow test rig. , 2015, , . | | Ο |
| 20 | Smart access to small lot manufacturing for systems integration. , 2018, , . | | 0 |
| 21 | Quality assurance of encapsulation architecture, including subsequent washing process for permanently mounted wearable sensors. , 2018, , . | | 0 |